DISCRETE SEMICONDUCTORS



Preliminary specification File under Discrete Semiconductors, SC08b 1996 Feb 08



# **UHF** power transistor

## **BLV904**

#### FEATURES

- Emitter ballasting resistors for optimum temperature profile
- · Gold metallization ensures excellent reliability
- Internal input matching to achieve high power gain and easy design of wideband circuits.

#### DESCRIPTION

NPN silicon planar epitaxial transistor encapsulated in a 8-lead SOT409B SMD package with a ceramic cap. All leads are isolated from the mounting base.

#### **PINNING - SOT409B**

PIN	SYMBOL	DESCRIPTION
1, 4, 5, 8	е	emitter
2, 3	b	base
6, 7	С	collector

### APPLICATIONS

• Common emitter class-AB operation in base stations in the 820 to 960 MHz frequency range.



### QUICK REFERENCE DATA

RF performance at  $T_{mb}$  = 25 °C in a common emitter test circuit.

MODE OF OPERATION	f	V <sub>CE</sub>	P <sub>L</sub>	G <sub>p</sub>	<sup>η</sup> с
	(MHz)	(V)	(W)	(dB)	(%)
CW, class-AB	960	26	5	≥11	≥50

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#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	60	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	28	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	4	V
I <sub>C</sub>	collector current (DC)		-	1.2	А
I <sub>C(AV)</sub>	average collector current		-	1.2	A
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 60 °C; note 1	-	14	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	operating junction temperature		_	200	°C

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-mb</sub>	thermal resistance from junction to mounting base	$P_{tot} = 14 \text{ W}; T_{mb} = 60 ^\circ\text{C}; \text{ note } 1$	10	K/W

#### Note to the "Limiting values" and "Thermal characteristics"

1. Transistor with metallized ground plane mounted on a printed-circuit board, see *"This handbook, Section Mounting and soldering"*.

#### CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>(BR)CBO</sub>	collector-base breakdown voltage	open emitter; I <sub>C</sub> = 5 mA	60	_	-	V
V <sub>(BR)CEO</sub>	collector-emitter breakdown voltage	open base; I <sub>C</sub> = 10 mA	28	-	-	V
V <sub>(BR)EBO</sub>	emitter-base breakdown voltage	open collector; I <sub>E</sub> = 0.5 mA	4	-	-	V
I <sub>CES</sub>	collector leakage current	$V_{CE} = 28 \text{ V}; \text{ V}_{BE} = 0$	-	-	3	mA
h <sub>FE</sub>	DC current gain	$V_{CE} = 20 \text{ V}; \text{ I}_{C} = 600 \text{ mA}$	30	-	120	
C <sub>c</sub>	collector capacitance	$V_{CB} = 26 \text{ V}; \text{ I}_{E} = \text{i}_{e} = 0; \text{ f} = 1 \text{ MHz}$	_	6	-	pF
C <sub>re</sub>	feedback capacitance	V <sub>CE</sub> = 26 V; I <sub>C</sub> = 0; f = 1 MHz	-	2.5	-	pF

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### **APPLICATION INFORMATION**

RF performance at  $T_{mb}$  = 25 °C in a common emitter test circuit.

MODE OF OPERATION	f	V <sub>CE</sub>	I <sub>CQ</sub>	P <sub>L</sub>	G <sub>p</sub>	ղշ
	(MHz)	(V)	(mA)	(W)	(dB)	<b>(%)</b>
CW, class-AB	960	26	15	5	≥11 typ. 12	≥50

#### **Ruggedness in class-AB operation**

The BLV904 is capable of withstanding a load mismatch corresponding to VSWR = 20 : 1 through all phases under the following conditions: f = 960 MHz;  $V_{CE} = 26 \text{ V}$ ;  $I_{CQ} = 15 \text{ mA}$ ;  $P_L = 5 \text{ W}$ ;  $T_{mb} = 25 \text{ °C}$ .





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#### Preliminary specification

### BLV904

#### PACKAGE OUTLINE



#### DEFINITIONS

Data Sheet Status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information				
Where application information is given, it is advisory and does not form part of the specification.				

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.